

## Description

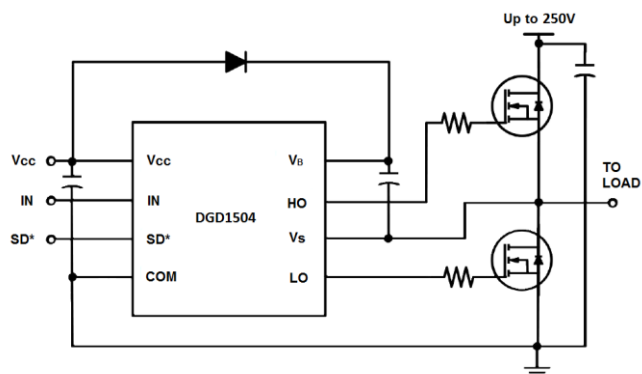
The DGD1504 is a high-voltage / high-speed gate driver capable of driving N-channel MOSFETs and IGBTs in a half bridge configuration. High-voltage processing techniques enable the DGD1504's high side to switch to 250V in a bootstrap operation.

The DGD1504 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with controlling devices. The driver outputs feature high-pulse current buffers designed for minimum driver cross conduction. The DGD1504 has a fixed internal deadtime of 430ns (typical).

The DGD1504 is offered in the SO-8 (Type TH) package and operates over an extended -40°C to +125°C temperature range.

## Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers



Typical Configuration

## Features

- Floating High-Side Driver in Bootstrap Operation to 250V
- Drives Two N-Channel MOSFETs or IGBTs in a Half Bridge Configuration
- 290mA Source / 600mA Sink Output Current Capability
- Outputs Tolerant to Negative Transients
- Internal Dead Time of 430ns to Protect MOSFETs
- Wide Low-Side Gate Driver Supply Voltage: 10V to 20V
- Logic Input (IN and SD\*) 3.3V Capability
- Schmitt Triggered Logic Inputs
- Undervoltage Lockout for V<sub>CC</sub> (Logic and Low Side Supply)
- Extended Temperature Range: -40°C To +125°C
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

## Mechanical Data

- Case: SO-8 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads Solderable per MIL-STD-202, Method 208
- Weight: 0.074 grams (Approximate)



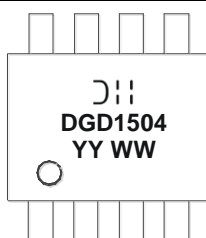
SO-8 (Type TH)  
Top View

## Ordering Information (Note 4)

| Product      | Marking | Reel Size (inch) | Tape Width (mm) | Quantity per Reel |
|--------------|---------|------------------|-----------------|-------------------|
| DGD1504S8-13 | DGD1504 | 13               | 12              | 2,500             |

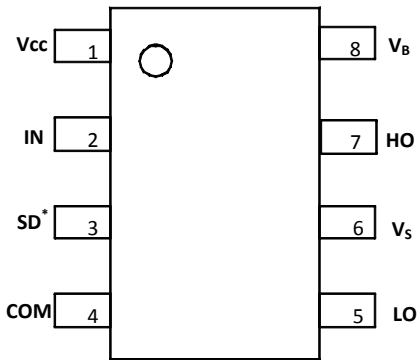
- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



- = Manufacturer's Marking
- DGD1504 = Product Type Marking Code
- YY = Year (ex: 16 = 2016)
- WW = Week (01 to 53)

**Pin Diagrams**

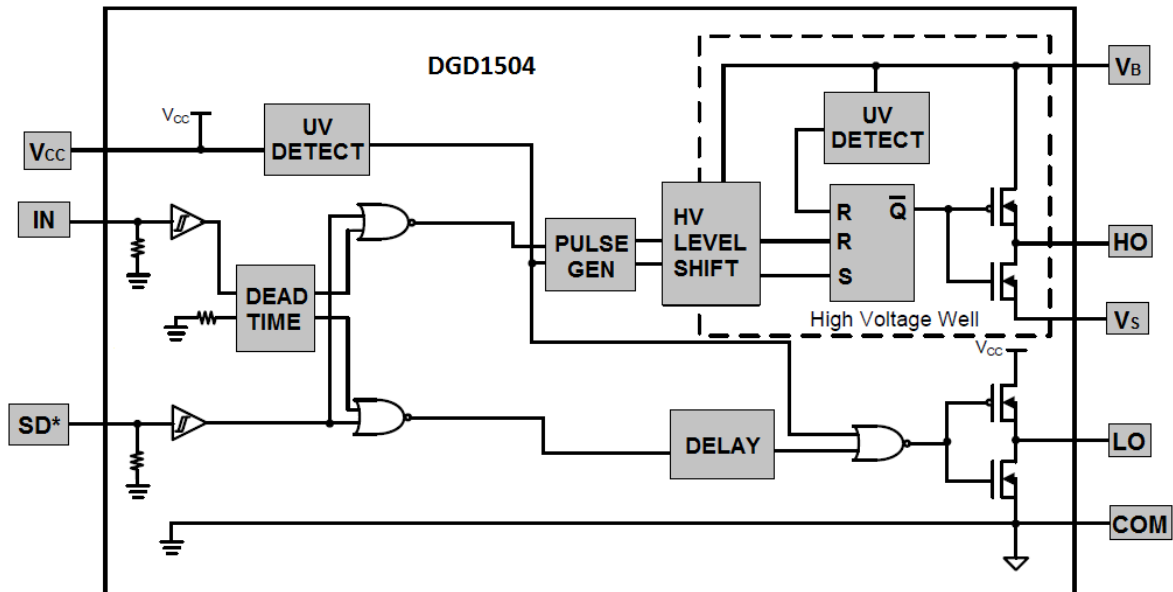


Top View: SO-8 (Type TH)

**Pin Descriptions**

| Pin Number | Pin Name        | Function   |
|------------|-----------------|--|
| 1          | V <sub>CC</sub> | Logic and Low Side Supply  |
| 2          | IN              | Logic Input for High-Side and Low-Side Gate Driver Outputs (HO and LO), in Phase with HO |
| 3          | SD*             | Logic input for Shutdown, Enabled Low  |
| 4          | COM             | Low-Side and Logic Return  |
| 5          | LO              | Low-Side Gate Drive Output   |
| 6          | V <sub>S</sub>  | High-Side Floating Supply Return   |
| 7          | HO              | High-Side Gate Drive Output  |
| 8          | V <sub>B</sub>  | High-Side Floating Supply  |

**Functional Block Diagram**



**Absolute Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

| Characteristic                           | Symbol      | Value                      | Unit |
|--|-------------|----------------------------|------|
| High-Side Floating Supply Voltage        | $V_B$       | -0.3 to +274               | V    |
| High-Side Floating Supply Offset Voltage | $V_S$       | $V_B - 24$ to $V_B + 0.3$  | V    |
| High-Side Floating Output Voltage        | $V_{HO}$    | $V_S - 0.3$ to $V_B + 0.3$ | V    |
| Offset Supply Voltage Transient          | $dV_S / dt$ | 50                         | V/ns |
| Low-Side Fixed Supply Voltage            | $V_{CC}$    | -0.3 to +24                | V    |
| Low-Side Output Voltage                  | $V_{LO}$    | -0.3 to $V_{CC} + 0.3$     | V    |
| Logic Input Voltage (IN and SD*)         | $V_{IN}$    | -0.3 to $V_{CC} + 0.3$     | V    |

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

| Characteristic                                    | Symbol          | Value       | Unit                      |
|---|-----------------|-------------|---------------------------|
| Power Dissipation Linear Derating Factor (Note 5) | $P_D$           | 0.625       | W                         |
| Thermal Resistance, Junction to Ambient (Note 5)  | $R_{\theta JA}$ | 200         | $^\circ\text{C}/\text{W}$ |
| Operating Temperature                             | $T_J$           | +150        | $^\circ\text{C}$          |
| Lead Temperature (Soldering, 10s)                 | $T_L$           | +300        |                           |
| Storage Temperature Range                         | $T_{STG}$       | -55 to +150 |                           |

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

**Recommended Operating Conditions**

| Parameter                                  | Symbol   | Min        | Max        | Unit             |
|--|----------|------------|------------|------------------|
| High Side Floating Supply Absolute Voltage | $V_B$    | $V_S + 10$ | $V_S + 20$ | V                |
| High Side Floating Supply Offset Voltage   | $V_S$    | (Note 6)   | 250        | V                |
| High Side Floating Output Voltage          | $V_{HO}$ | $V_S$      | $V_B$      | V                |
| Low Side Fixed Supply Voltage              | $V_{CC}$ | 10         | 20         | V                |
| Low Side Output Voltage                    | $V_{LO}$ | 0          | $V_{CC}$   | V                |
| Logic Input Voltage (IN and SD*)           | $V_{IN}$ | 0          | 5          | V                |
| Ambient Temperature                        | $T_A$    | -40        | +125       | $^\circ\text{C}$ |

Note: 6. Logic operation for  $V_S$  of -5V to +250V. Logic state held for  $V_S$  of -5V to  $-V_{BS}$ .

**DC Electrical Characteristics** ( $V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ) = 15V, @ $T_A$  = +25°C, unless otherwise specified.) (Note 7)

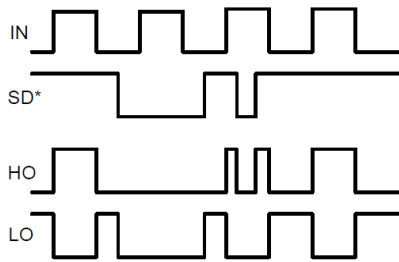
| Parameter   | Symbol      | Min | Typ  | Max | Unit    | Condition                       |
|---|-------------|-----|------|-----|---------|---------------------------------|
| Logic "1" (IN) & Logic "0" (SD*) Input Voltage        | $V_{IH}$    | 2.5 | –    | –   | V       | $V_{CC} = 10V$ to 20V           |
| Logic "0" (IN) & Logic "1" (SD*) Input Voltage        | $V_{IL}$    | –   | –    | 0.8 | V       | $V_{CC} = 10V$ to 20V           |
| High Level Output Voltage, $V_{BIAS} - V_O$           | $V_{OH}$    | –   | 0.05 | 0.2 | V       | $I_O = 2mA$                     |
| Low Level Output Voltage, $V_O$                       | $V_{OL}$    | –   | 0.02 | 0.1 | V       | $I_O = 2mA$                     |
| Offset Supply Leakage Current                         | $I_{LK}$    | –   | –    | 50  | $\mu A$ | $V_B = V_S = 250V$              |
| Quiescent $V_{BS}$ Supply Current                     | $I_{BSQ}$   | –   | 60   | 100 | $\mu A$ | $V_{IN} = 0V$ or 5V             |
| Quiescent $V_{CC}$ Supply Current                     | $I_{CCQ}$   | –   | 350  | 500 | $\mu A$ | $V_{IN} = 0V$ or 5V             |
| Logic "1" Input Bias Current                          | $I_{IN+}$   | –   | 3.0  | 10  | $\mu A$ | $V_{IN} = 5V$ , $SD^* = 0V$     |
| Logic "0" Input Bias Current                          | $I_{IN-}$   | –   | –    | 5.0 | $\mu A$ | $V_{IN} = 0V$ , $SD^* = 5V$     |
| $V_{CC}$ Supply Undervoltage Positive Going Threshold | $V_{CCUV+}$ | 7.4 | 8.5  | 9.6 | V       | –                               |
| $V_{CC}$ Supply Undervoltage Negative Going Threshold | $V_{CCUV-}$ | 7.1 | 7.8  | 8.8 | V       | –                               |
| $V_{BS}$ Supply Undervoltage Positive Going Threshold | $V_{BSUV+}$ | 5.5 | 6.5  | 7.5 | V       | –                               |
| $V_{BS}$ Supply Undervoltage Negative Going Threshold | $V_{BSUV-}$ | 5.3 | 6.3  | 7.3 | V       | –                               |
| Output High Short Circuit Pulsed Current              | $I_{O+}$    | 130 | 290  | –   | mA      | $V_O = 0V$ , $PW \leq 10\mu s$  |
| Output Low Short Circuit Pulsed Current               | $I_{O-}$    | 270 | 600  | –   | mA      | $V_O = 15V$ , $PW \leq 10\mu s$ |

Note: 7. The  $V_{IN}$  and  $I_{IN}$  parameters are applicable to the two logic pins: IN and SD\*. The  $V_O$  and  $I_O$  parameters are applicable to the respective output pins: HO and LO.

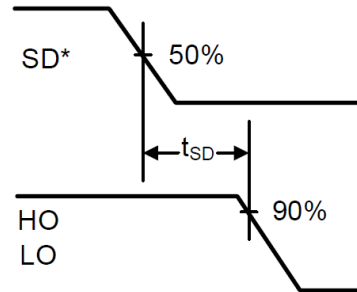
**AC Electrical Characteristics** ( $V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ) = 15V,  $C_L = 1000pF$ , @ $T_A$  = +25°C, unless otherwise specified.)

| Parameter                                  | Symbol    | Min | Typ | Max | Unit | Condition    |
|--|-----------|-----|-----|-----|------|--------------|
| Turn-on Propagation Delay                  | $t_{ON}$  | –   | 680 | 820 | ns   | $V_S = 0V$   |
| Turn-off Propagation Delay                 | $t_{OFF}$ | –   | 150 | 220 | ns   | $V_S = 250V$ |
| Shutdown Propagation Delay                 | $t_{SD}$  | –   | 160 | 220 | ns   | –            |
| Delay Matching, HO and LO Turn-on/Turn-off | $t_{DM}$  | –   | –   | 60  | ns   | –            |
| Turn-on Rise Time                          | $t_R$     | –   | 70  | 170 | ns   | $V_S = 0V$   |
| Turn-off Fall Time                         | $t_F$     | –   | 35  | 90  | ns   | $V_S = 0V$   |
| Deadtime: $t_{DT LO-HO}$ & $t_{DT HO-LO}$  | $t_{DT}$  | 300 | 430 | 550 | ns   | –            |

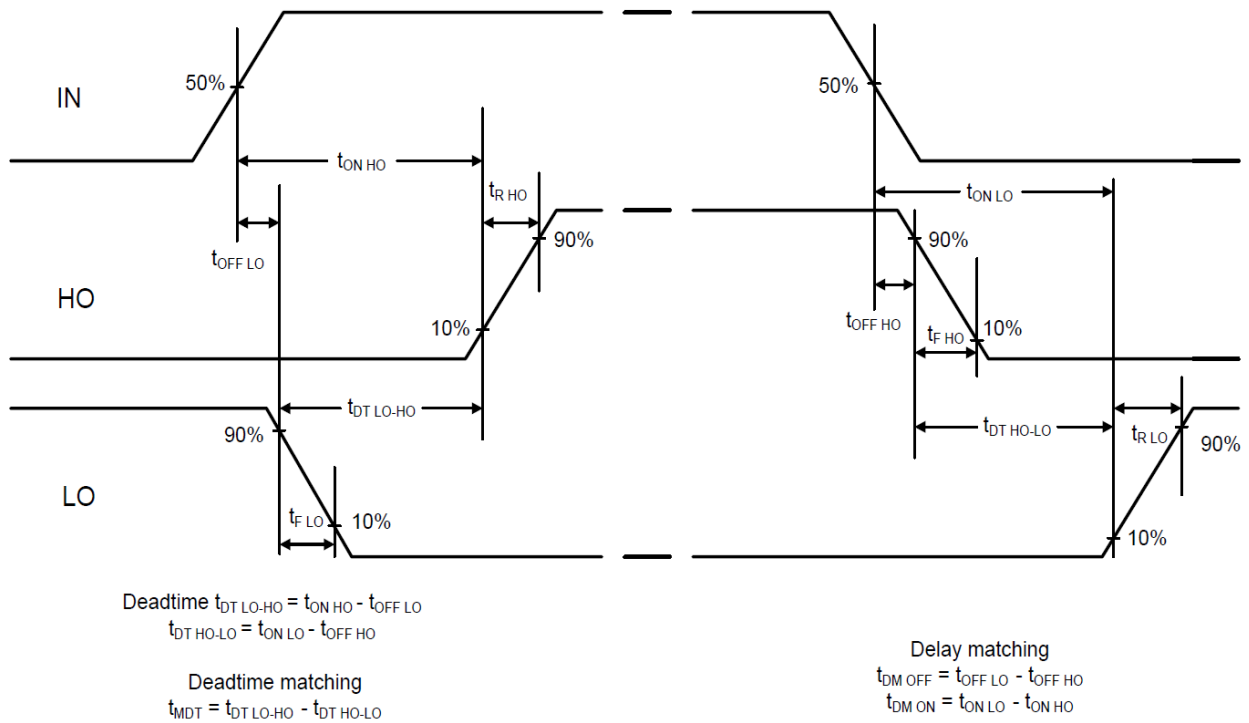
**Timing Waveforms**



**Figure 1.** Input / Output Timing Diagram

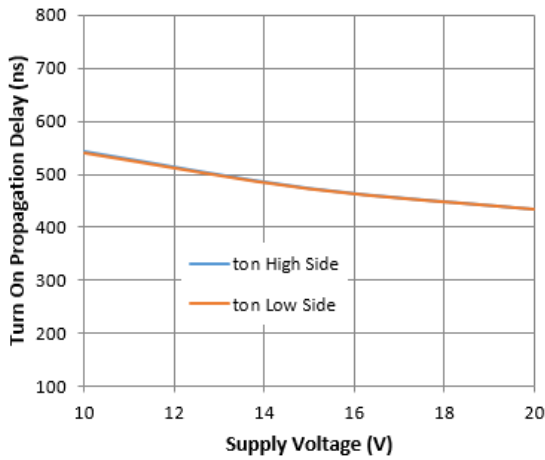


**Figure 2.** Shutdown Waveform Definition

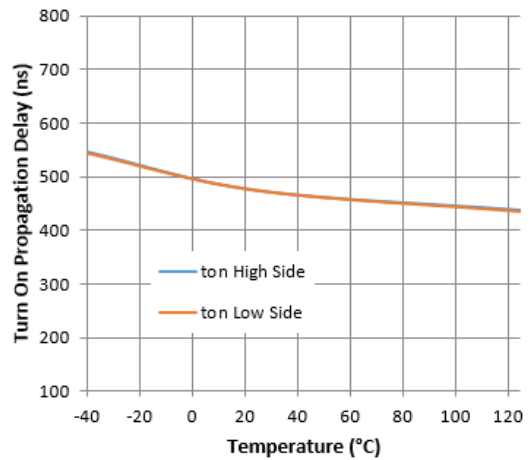


**Figure 3.** Switching Time Waveform Definitions

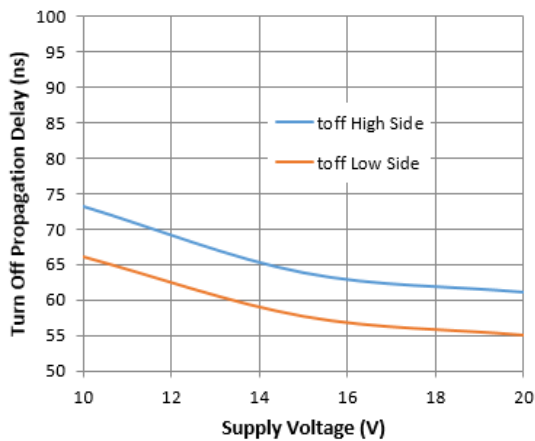
**Typical Performance Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)



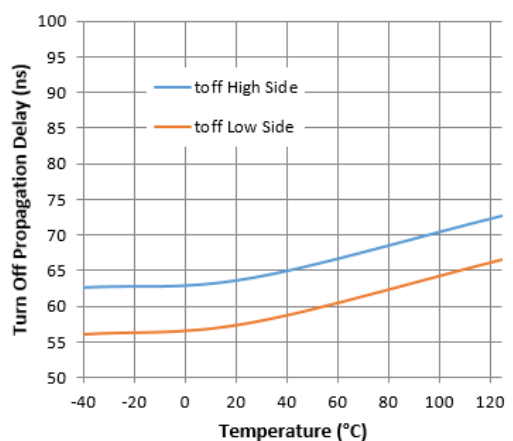
**Figure 4.** Turn-on Propagation Delay vs. Supply Voltage



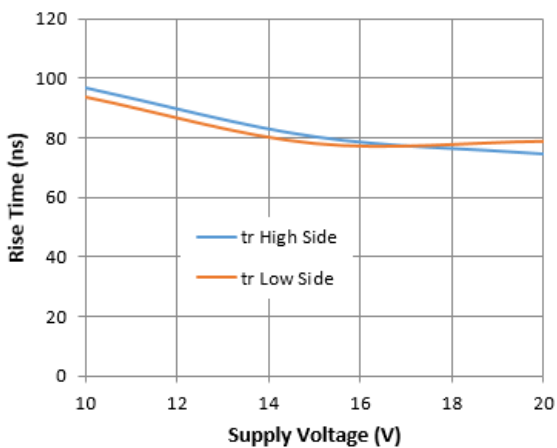
**Figure 5.** Turn-on Propagation Delay vs. Temperature



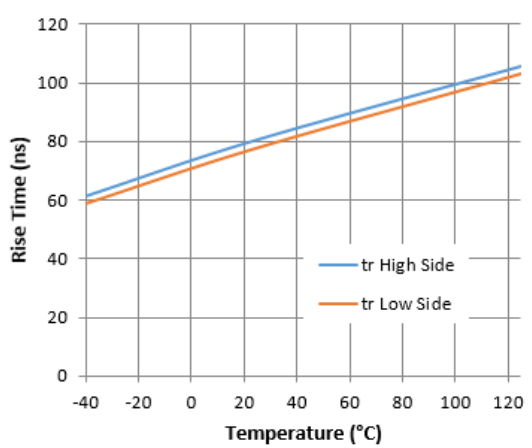
**Figure 6.** Turn-off Propagation Delay vs. Supply Voltage



**Figure 7.** Turn-off Propagation Delay vs. Temperature

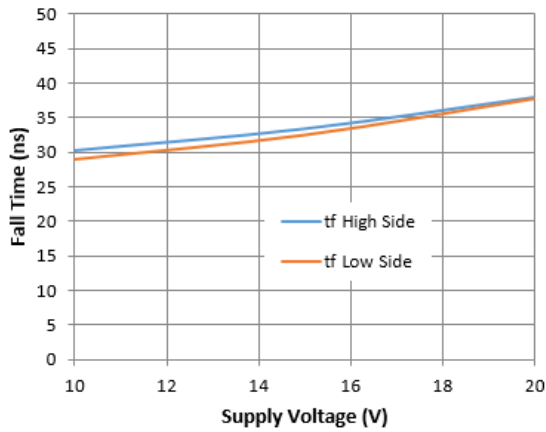


**Figure 8.** Rise Time vs. Supply Voltage

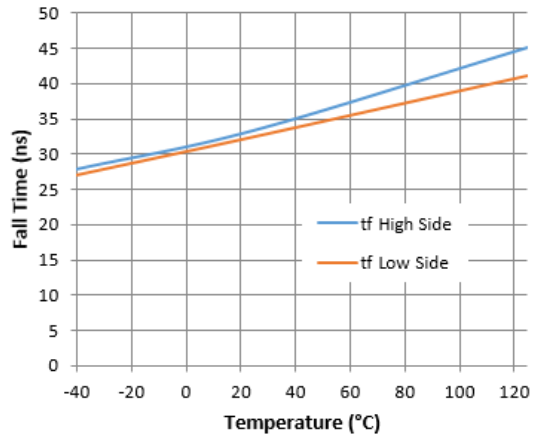


**Figure 9.** Rise Time vs. Temperature

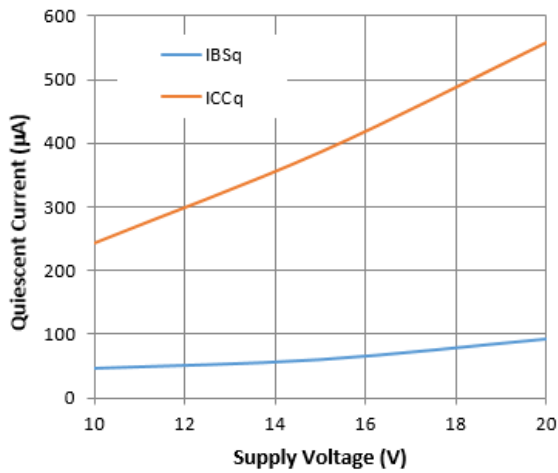
**Typical Performance Characteristics (Cont.)**



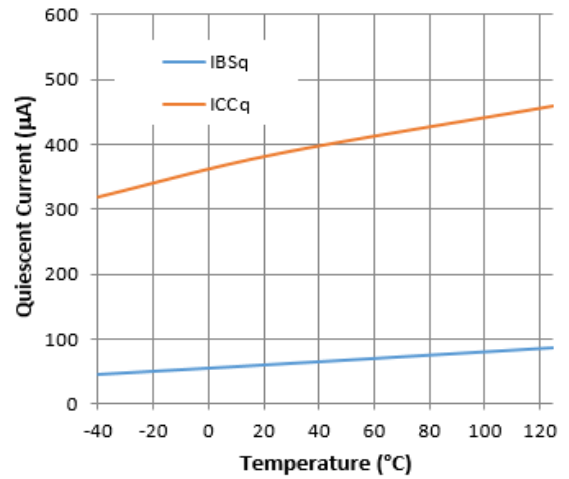
**Figure 10.** Fall Time vs. Supply Voltage



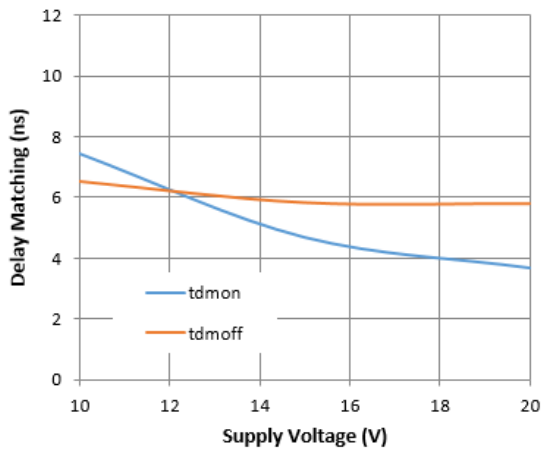
**Figure 11.** Fall Time vs. Temperature



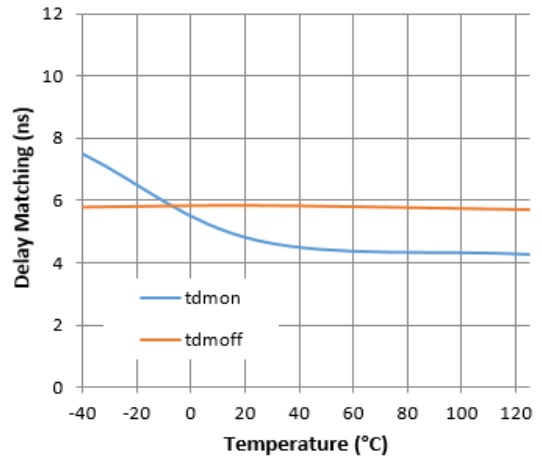
**Figure 12.** Quiescent Current vs. Supply Voltage



**Figure 13.** Quiescent Current vs. Temperature

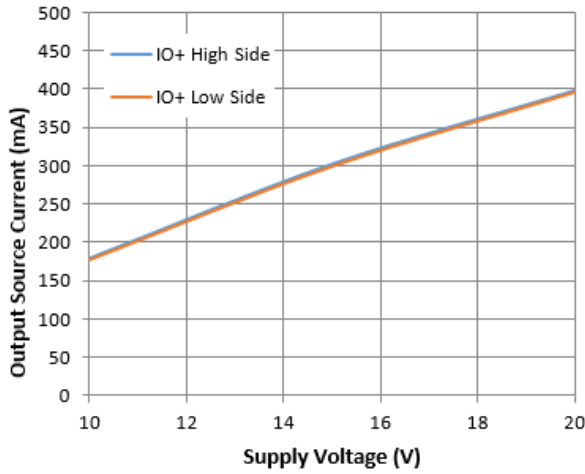


**Figure 14.** Delay Matching vs. Supply Voltage

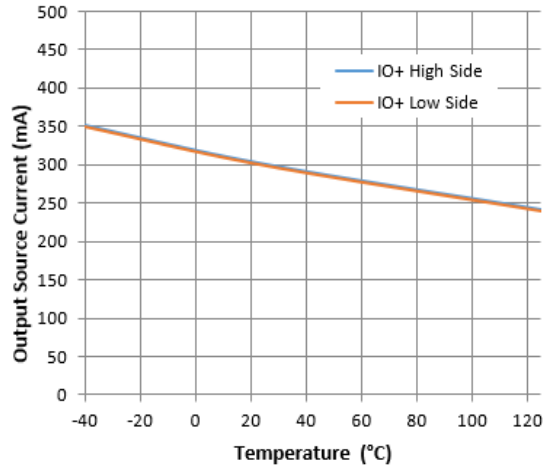


**Figure 15.** Delay Matching vs. Temperature

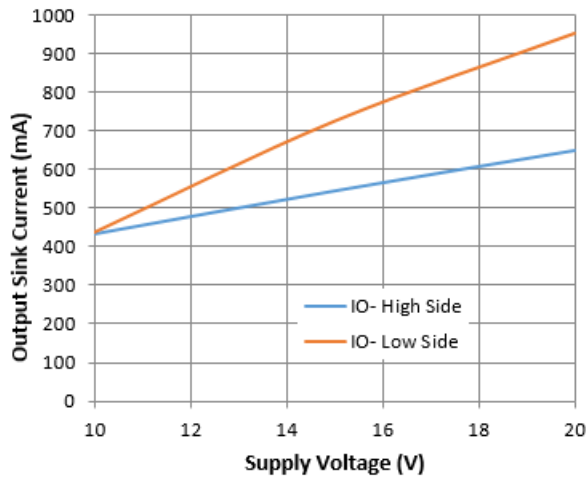
**Typical Performance Characteristics (Cont.)**



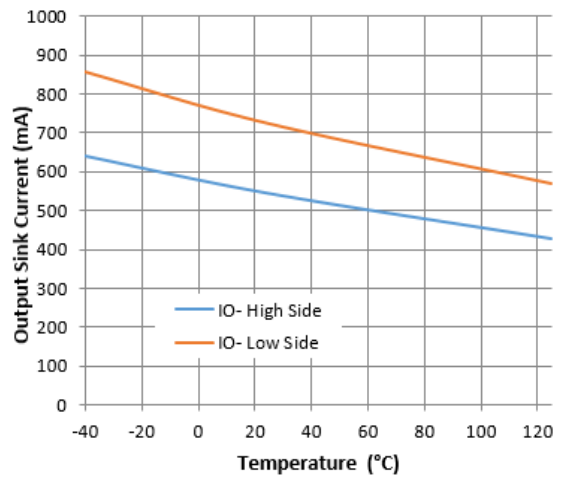
**Figure 16.** Output Source Current vs. Supply Voltage



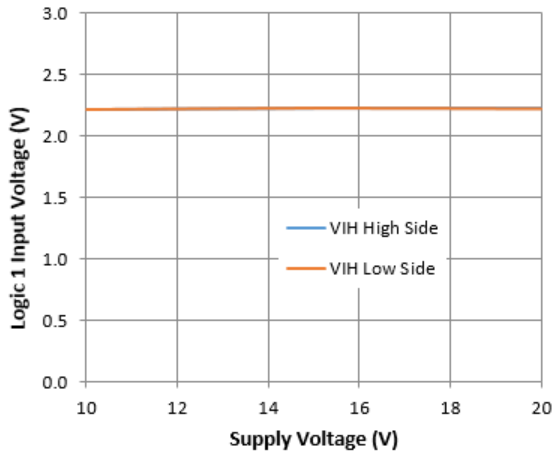
**Figure 17.** Output Source Current vs. Temperature



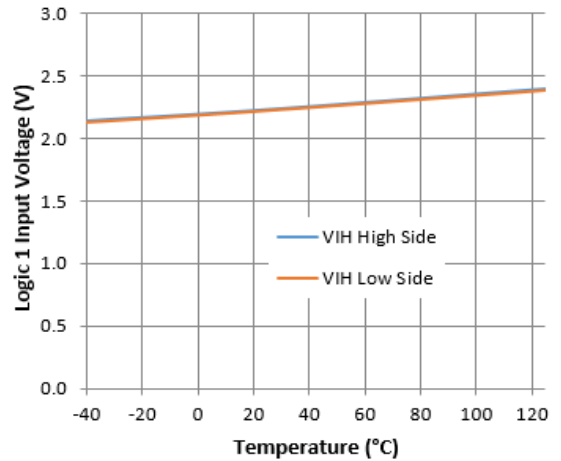
**Figure 18.** Output Sink Current vs. Supply Voltage



**Figure 19.** Output Sink Current vs. Temperature



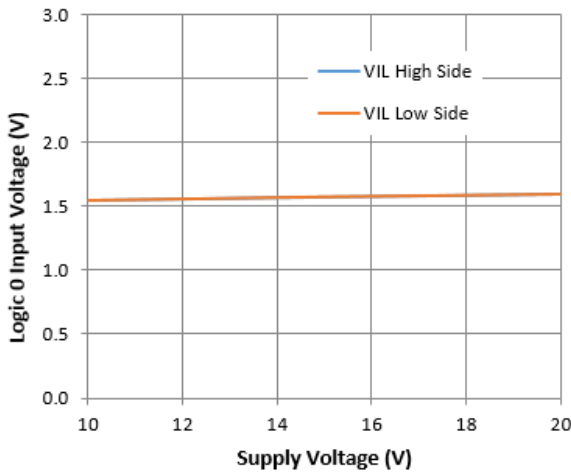
**Figure 20.** Logic 1 Input Voltage vs. Supply Voltage



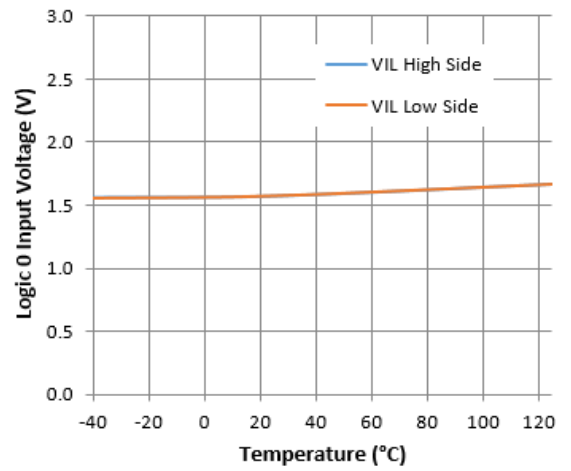
**Figure 21.** Logic 1 Input Voltage vs. Temperature



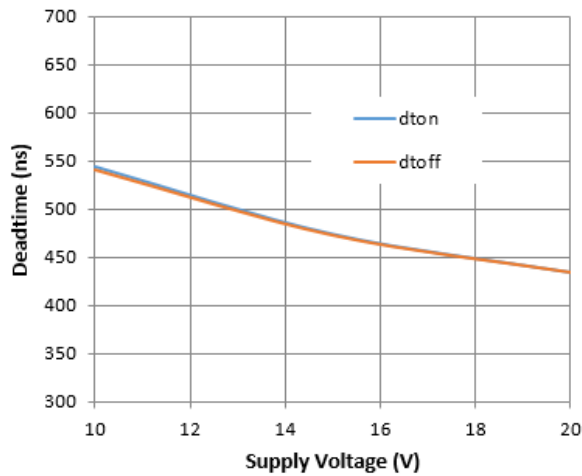
**Typical Performance Characteristics (Cont.)**



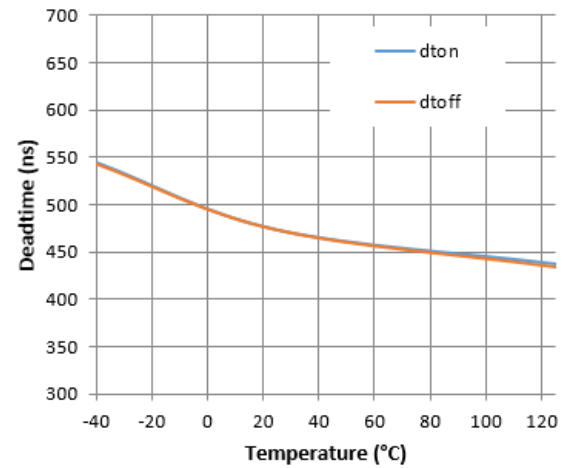
**Figure 22.** Logic 0 Input Voltage vs. Supply Voltage



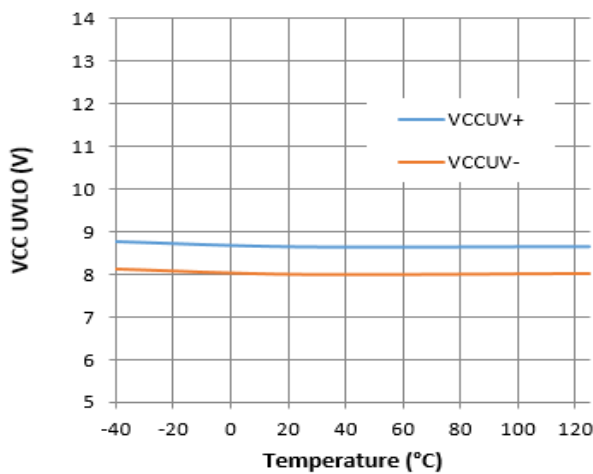
**Figure 23.** Logic 0 Input Voltage vs. Temperature



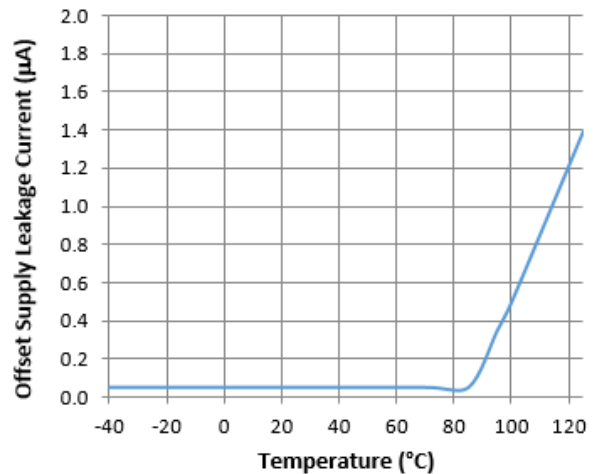
**Figure 24.** Deadtime vs. Supply Voltage



**Figure 25.** Deadtime vs. Temperature



**Figure 26.** VCC UVLO vs. Temperature

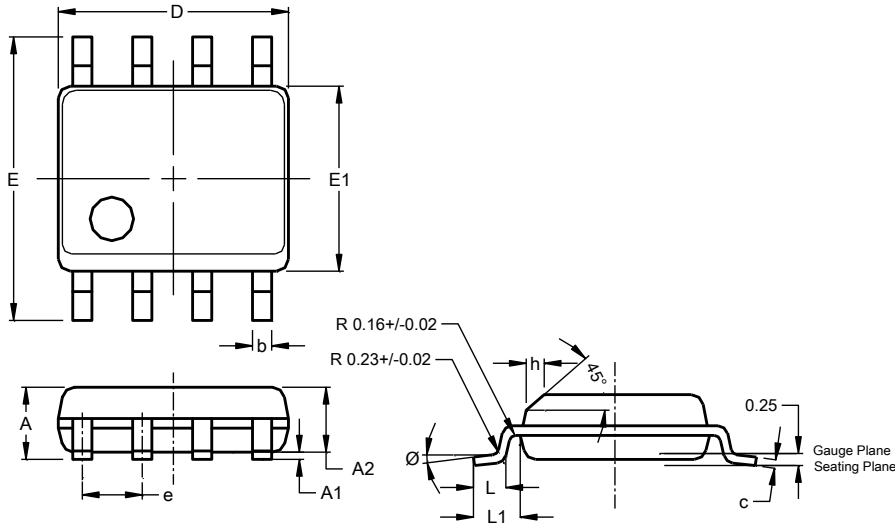


**Figure 27.** Offset Supply Leakage Current vs. Temperature

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SO-8 (Type TH)**

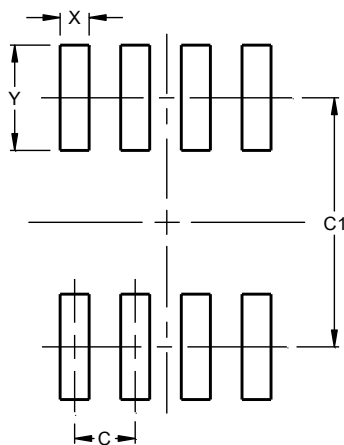


| SO-8 (Type TH)       |       |       |      |
|----------------------|-------|-------|------|
| Dim                  | Min   | Max   | Typ  |
| A                    | 1.35  | 1.75  | --   |
| A1                   | 0.10  | 0.25  | --   |
| A2                   | --    | --    | 1.45 |
| b                    | 0.35  | 0.51  | --   |
| c                    | 0.190 | 0.248 | --   |
| D                    | 4.80  | 5.00  | 4.90 |
| E                    | 5.80  | 6.20  | 6.00 |
| E1                   | 3.80  | 4.00  | 3.90 |
| e                    | --    | --    | 1.27 |
| h                    | 0.25  | 0.50  | --   |
| L                    | 0.41  | 1.27  | --   |
| L1                   | --    | --    | 1.04 |
| ∅                    | 0°    | 8°    | --   |
| All Dimensions in mm |       |       |      |

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SO-8 (Type TH)**



| Dimensions | Value (in mm) |
|------------|---------------|
| C          | 1.27          |
| C1         | 5.20          |
| X          | 0.60          |
| Y          | 2.20          |

Note : For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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